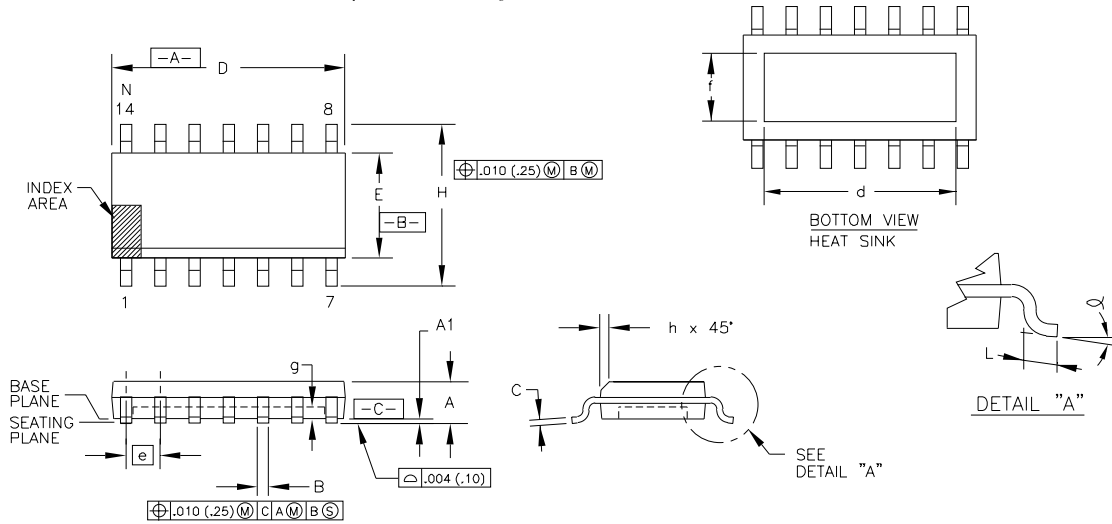


Package Number 235-1 - 14-Lead SOIC With Exposed Heat Slug



DIM	INCHES		MILLIMETERS		NO E	DIM	INCHES		MILLIMETERS		NO E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.0532	.0688	1.35	1.75		∞	0"	8"	0"	8"	
A1	.004	.0098	0.10	0.25							
B	.013	.020	0.33	0.51	7						
C	.0075	.0098	0.19	0.25							
D	.3367	.3444	8.55	8.75	2						
d	.270	.290	6.86	7.37	9						
E	.1497	.1574	3.80	4.00	3						
e	.050	BASIC	1.27	BASIC							
f	.090	.110	2.29	2.79	9						
g	.016	.018	0.41	0.46	9						
H	.2284	.244	5.80	6.20							
h	.0099	.0196	0.25	0.50	4						
L	.016	.050	0.40	1.27	5						
N	14		14		6						

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
- DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
- THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE

- LOCATED WITHIN THE CROSS-HATCHED AREA.
- L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- N IS THE NUMBER OF TERMINAL POSITIONS.
- THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
- LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.
- HEAT SLUG DIMENSIONS.

PACKAGE NUMBER:	ZZ235-1	REV.:	A
JEDEC NUMBER:	MS-012-AB		

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